

#### **Features**

- Small double-end package
- High reliability
- High Reverse Breakdown
- High Sensitivity
- Fast Response time
- RoHS compliance

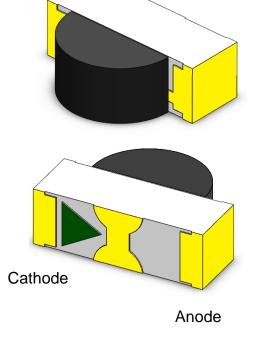
### **Applications**

- Infrared sensor
- Light barrier
- Infrared Touch Panel Solutions

### **Description**

The PDP93010BP20 is a silicon photo diode housed in a miniature SMD package. The device comes with a superior filtering for visible light by utilizing special black molding compound.

### **Package Outline**



#### **Schematic**



## Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
$V_{R}$	Reverse Voltage	33	V	
T <sub>opr</sub>	Operating Temperature	-40 ~ +85	°C	
T <sub>stg</sub>	Storage Temperature	-40 ~ +100	°C	
T <sub>sol</sub>	Soldering Temperature	260	°C	1
PD	Power Dissipation at(or below) 25°C Free Air Temperature	140	mW	
R <sub>THJA</sub>	Junction to Ambient Thermal Resistance	530	°C/W	



### Electro-Optical Characteristics TA = 25°C (unless otherwise specified)

### **Optical Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
λ	Spectral Bandwidth	-	700	-	1100	nm	
λР	Peak Sensitivity	-	-	900	-	nm	
04/2	View Angle at X axis	\/ <sub>-</sub>	-	±72.5	-	doa	2
θ1/2	View Angle at Y axis	V <sub>R</sub> =5V	-	±67.5	-	deg	2

#### **Electrical Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
	Dark Correct	Ee=0mW /cm <sup>2</sup>			40	Λ	
I <sub>D</sub>	Dark Current	V <sub>R</sub> =10V	-	-	10	nA	
\/	Davaraa Braakdayya Valtaga	Ee=0mW /cm <sup>2</sup>	22	200	- V		
V <sub>BR</sub>	Reverse Breakdown Voltage	I <sub>R</sub> =100uA	33	200		V	
Voc	Open-Circuit Voltage	Ee=1mW /cm <sup>2</sup>	-	0.42	-	V	
Isc	Short-Circuit Current	λ <sub>P</sub> =940nm	-	1.72	-	μΑ	
l-		Ee=1mW /cm <sup>2</sup>	1.3	1.90	-	μA	
I <sub>R</sub>	Reverse Light Current	λ <sub>P</sub> =940nm, V <sub>R</sub> =5V		1.90			
C-	Total Capacitance	Ee=0mW /cm²	7.89 -		ηE		
Ст	Total Capacitatice	f=1MHz ,V <sub>R</sub> =5V	-	7.09	-	pF	

#### **Switching Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
t <sub>r</sub>	Rise Time	V 5V P 10k0	-	500	-	20	
t <sub>f</sub>	Fall Time	$V_R = 5V$ , $R_L = 10k\Omega$	-	500	-	ns	

#### Notes:

1 : Soldering time  $\leq$  5 seconds.

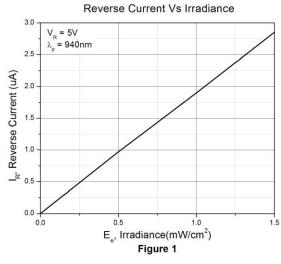


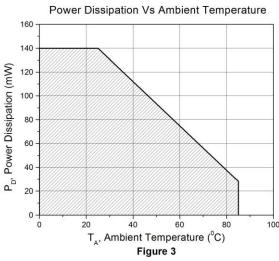


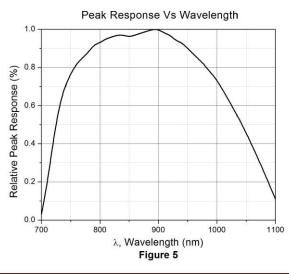
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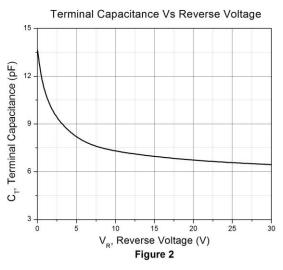
# PDP93010BP20 SMD Type Photo Diode

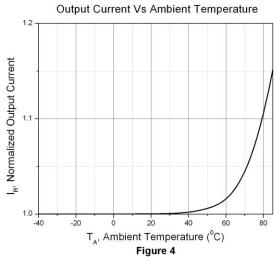
### **Typical Characteristic Curves**

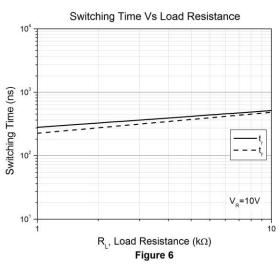








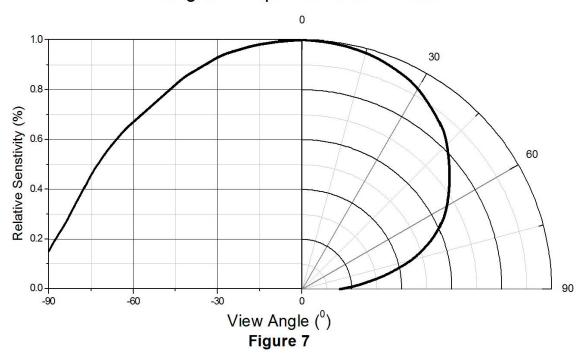




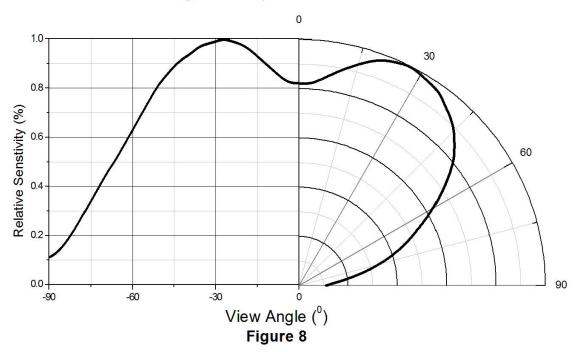


### **Typical Characteristic Curves**

### Angular Displacement at X axis

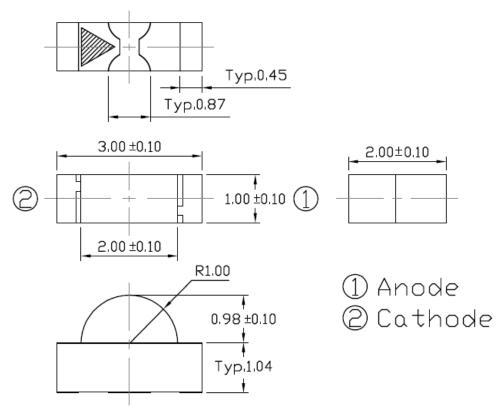


### Angular Displacement at Y axis

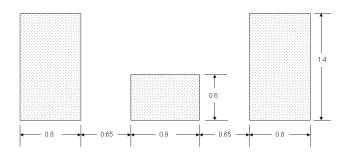




#### Package Dimension All dimensions are in mm, unless otherwise stated



### Recommended Soldering Mask All dimensions are in mm, unless otherwise stated

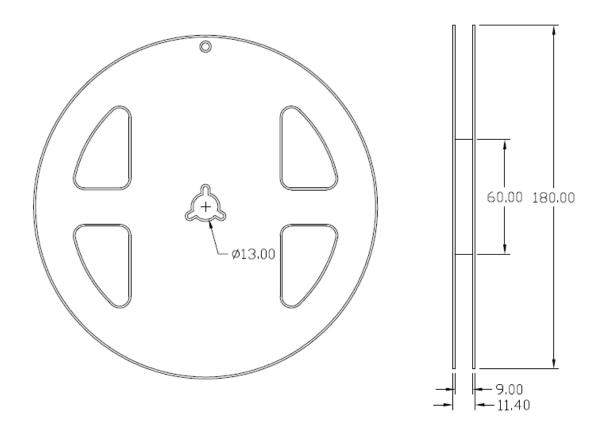


### **Ordering Information**

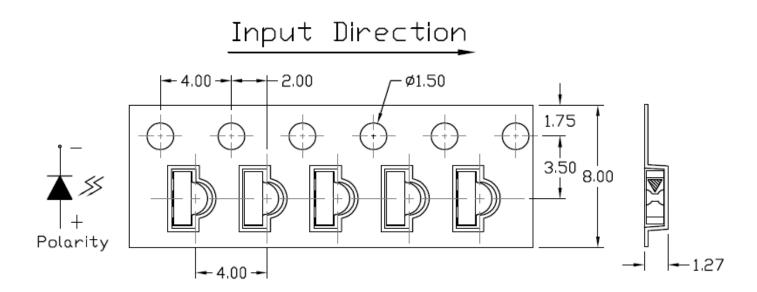
Part Number	Description	Quantity
PDP93010BP20	Tape & Reel	3000 pcs



### Reel Dimension All dimensions are in mm, unless otherwise stated

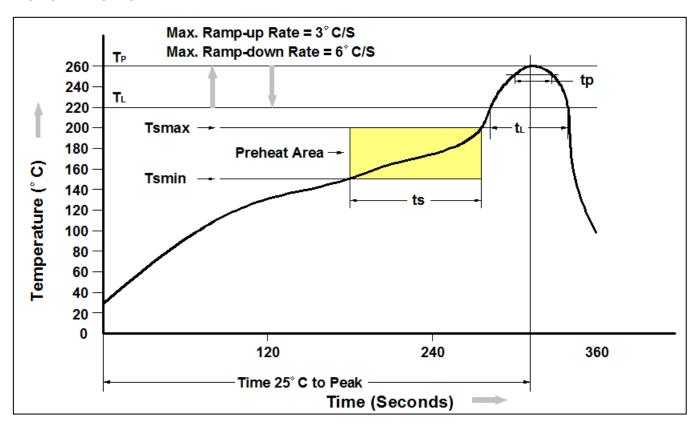


Tape Dimension All dimensions are in mm, unless otherwise stated





#### **Reflow Profile**



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t⊳)	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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